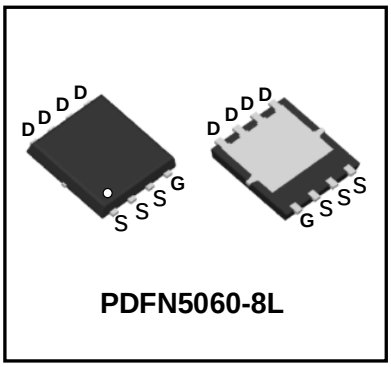
# WMB023N03LG2

## 30V N-Channel Enhancement Mode Power MOSFET

## Description

WMB023N03LG2 uses Wayon's 2nd generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.

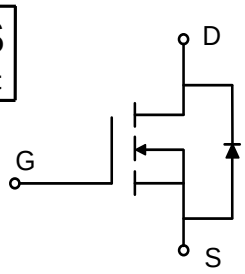



PDFN5060-8L

## Features

- $V_{DS}$ = 30V, $I_D$ = 85A(Package Limited)
  $R_{DS(on)}$ < 2.3mΩ @ $V_{GS}$ = 10V
  $R_{DS(on)}$ < 3.7mΩ @ $V_{GS}$ = 4.5V
- Low $R_{DS}$(on)
- Low Gate Charge
- 100% EAS Guaranteed
- RoHS and Halogen-Free Compliant

RoHS compliant




## Applications

- Power Management in Switches
- DC/DC Converter

### Absolute Maximum Ratings

| Parameter | | Symbol | Value | Unit |
|---|---|---|---|---|
| Drain-Source Voltage | | $V_{DS}$ | 30 | V |
| Gate-Source Voltage | | $V_{GS}$ | ±20 | V |
| Continuous Drain Current[1](Package Limited) | $T_C$=25℃ | $I_D$ | 85 | A |
| | $T_C$=100℃ | | 67 | |
| Pulsed Drain Current[2] | | $I_{DM}$ | 251 | A |
| Single Pulse Avalanche Energy[3] | | EAS | 151 | mJ |
| Avalanche Current | | $I_{AS}$ | 50 | A |
| Total Power Dissipation[4] | $T_C$=25℃ | $P_D$ | 49 | W |
| Operating Junction and Storage Temperature Range | | $T_J$ , $T_{STG}$ | -55 to 150 | °C |

### Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|---|---|---|---|
| Thermal Resistance from Junction-to-Ambient[1] | $R_{\theta JA}$ | 50.1 | °C/W |
| Thermal Resistance from Junction-to-Case[1] | $R_{\theta JC}$ | 2.5 | °C/W |

## Electrical Characteristics $T_c$ = 25°C, unless otherwise noted

| Parameter | | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|---|
| **Static Characteristics** | | | | | | | |
| Drain-Source Breakdown Voltage | | $V_{(BR)DSS}$ | $V_{GS}$ = 0V, $I_D$ = 250μA | 30 | - | - | V |
| Gate-body Leakage Current | | $I_{GSS}$ | $V_{DS}$ = 0V, $V_{GS}$ = ±20V | - | - | ±100 | nA |
| Zero Gate Voltage Drain Current | $T_J$=25℃ | $I_{DSS}$ | $V_{DS}$ = 24V, $V_{GS}$ = 0V | - | - | 1 | μA |
| | $T_J$=55℃ | | | - | - | 5 | |
| Gate-Threshold Voltage | | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$, $I_D$ = 250μA | 1.2 | 1.6 | 2.2 | V |
| Drain-Source On-Resistance[2] | | $R_{DS(on)}$ | $V_{GS}$ = 10V, $I_D$ = 20A | - | 1.7 | 2.3 | mΩ |
| | | | $V_{GS}$ = 4.5V, $I_D$ = 20A | - | 2.5 | 3.7 | |
| Forward Transconductance | | $g_{fs}$ | $V_{DS}$ = 5V, $I_D$ = 20A | - | 90 | - | S |
| **Dynamic Characteristics** | | | | | | | |
| Input Capacitance | | $C_{iss}$ | $V_{DS}$ = 15V, $V_{GS}$ = 0V, f = 1MHz | - | 3020 | - | pF |
| Output Capacitance | | $C_{oss}$ | | - | 1580 | - | |
| Reverse Transfer Capacitance | | $C_{rss}$ | | - | 205 | - | |
| **Switching Characteristics** | | | | | | | |
| Gate Resistance | | $R_G$ | $V_{DS}$ = 0V, $V_{GS}$ =0V, f = 1MHz | - | 1.6 | - | Ω |
| Total Gate Charge(4.5V) | | $Q_g$ | $V_{GS}$ = 10V, $V_{DS}$ = 15V, $I_D$ = 20A | - | 21.5 | - | nC |
| Gate-Source Charge | | $Q_{gs}$ | | - | 12.8 | - | |
| Gate-Drain Charge | | $Q_{gd}$ | | - | 15 | - | |
| Turn-on Delay Time | | $t_{d(on)}$ | $V_{GS}$ = 10V, $V_{DS}$ = 15V, $R_G$ = 3.3Ω, $I_D$ = 20A | - | 12.2 | - | nS |
| Rise Time | | $t_r$ | | - | 6.5 | - | |
| Turn-off Delay Time | | $t_{d(off)}$ | | - | 38.2 | - | |
| Fall Time | | $t_f$ | | - | 11.8 | - | |
| **Drain-Source Body Diode Characteristics** | | | | | | | |
| Diode Forward Voltage[2] | | $V_{SD}$ | $I_S$ = 1A, $V_{GS}$ = 0V | - | - | 1.0 | V |
| Continuous Source Current[1] | | $I_S$ | $V_G$ = $V_D$= 0V , Force Current | - | - | 85 | A |

Notes:

1.The data tested by surface mounted on a 1 inch$^2$ FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.The EAS data shows Max. rating . The test condition is $V_{DD}$=25V, $V_{GS}$=10V, L=0.1mH, $I_{AS}$=50A

4.The power dissipation is limited by 150℃ junction temperature

5.The data is theoretically the same as $I_D$ and $I_{DM}$ , in real applications , should be limited by total power dissipation.

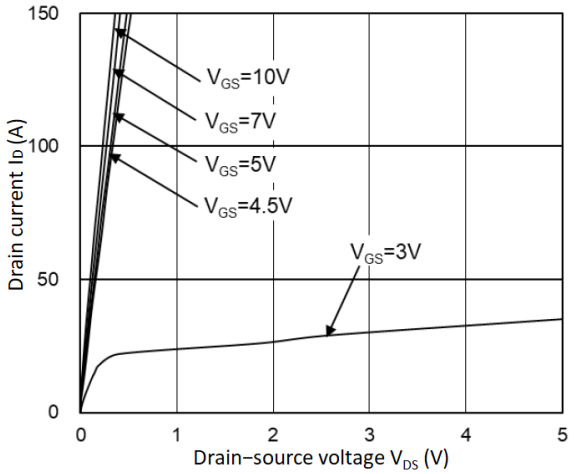



Figure 1. Output Characteristics

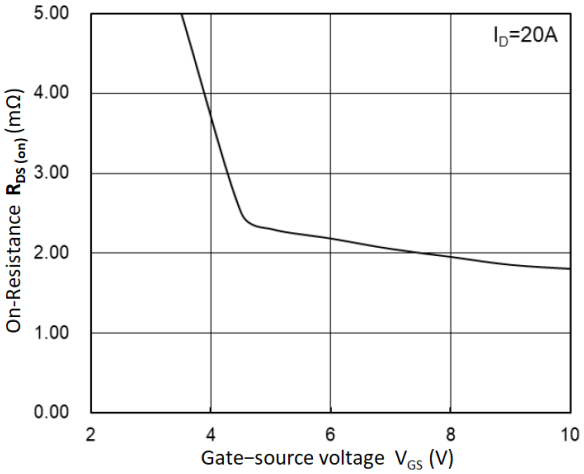



Figure 2. $R_{DS(on)}$ vs. $V_{GS}$

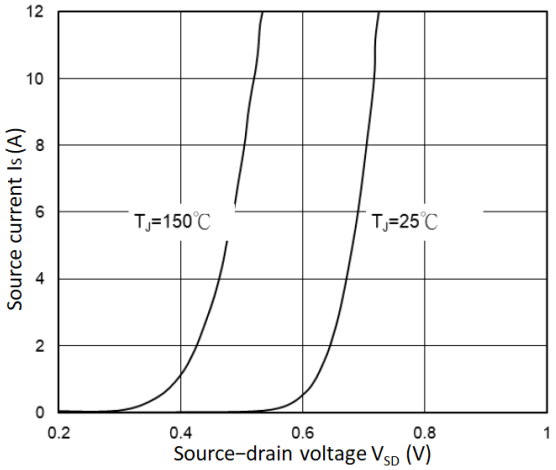



Figure 3. Forward Characteristics of Reverse

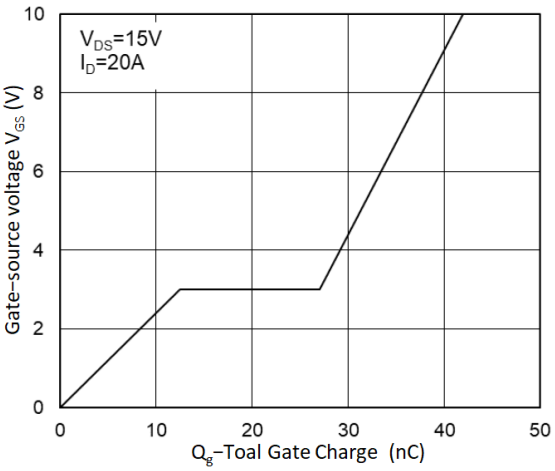



Figure 4. Gate Charge Characteristics

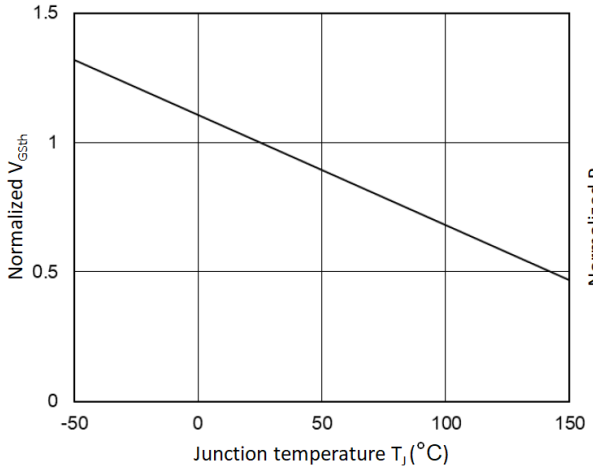



Figure 5. Normalized $V_{GSth}$ vs. $T_J$

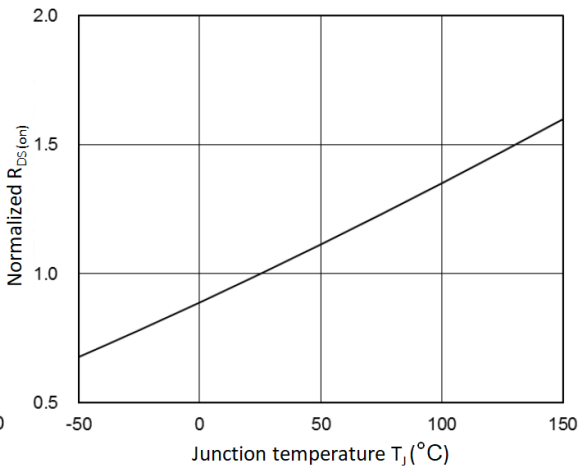



Figure 6. Normalized $R_{DS(on)}$ vs. $T_J$

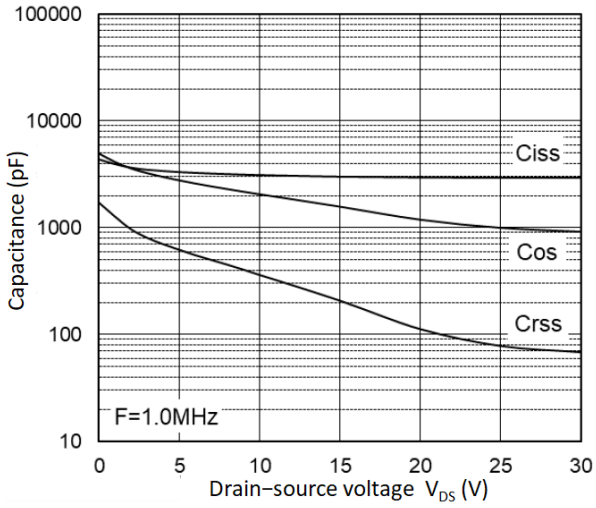



Figure 7. Capacitance Characteristics

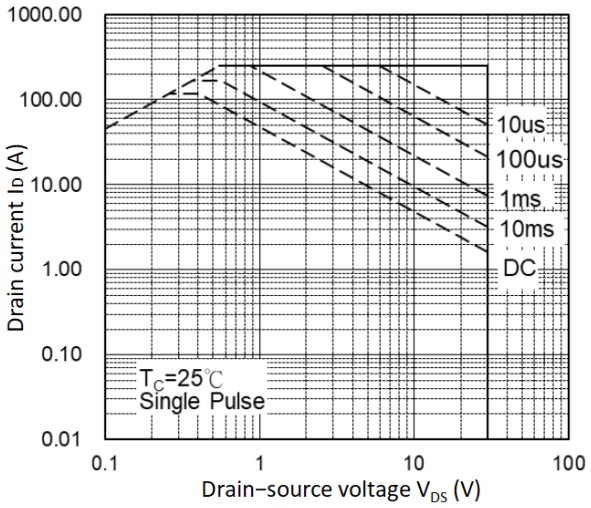



Figure 8. Safe Operating Area

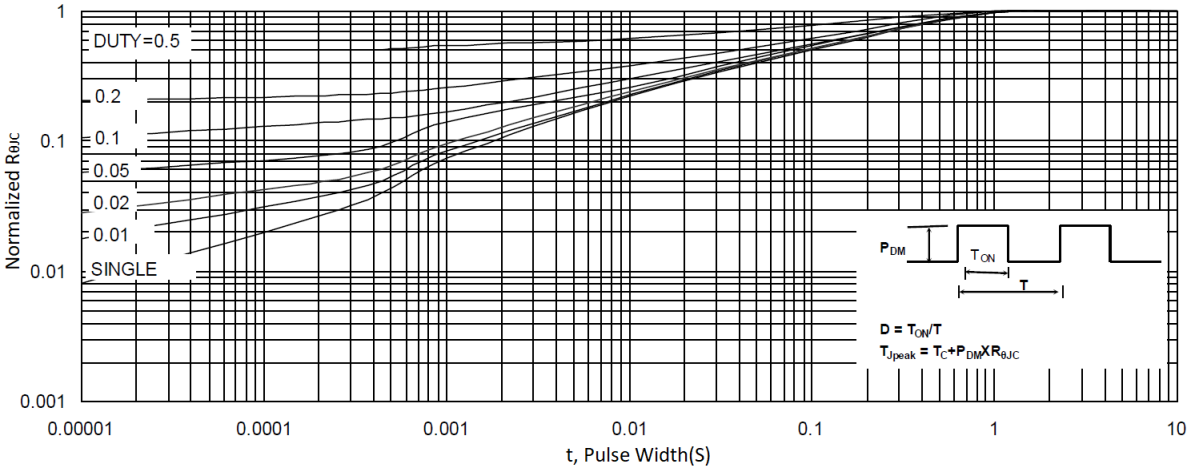



Figure 9. Normalized Maximum Transient Thermal Impedance

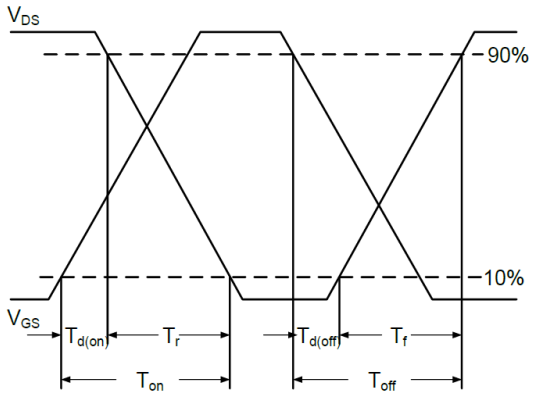



Figure 10. Switching Time Waveform

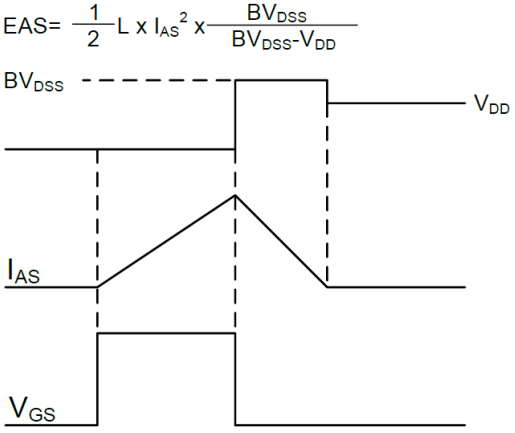
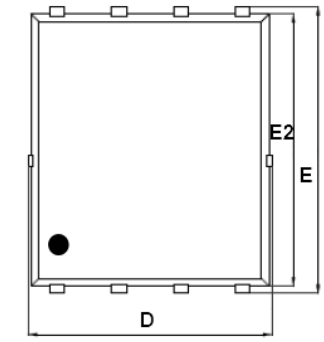
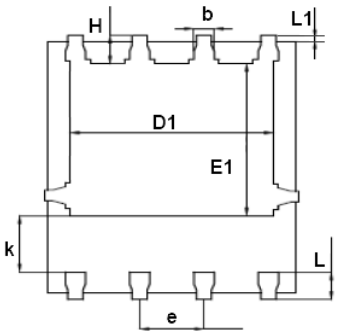


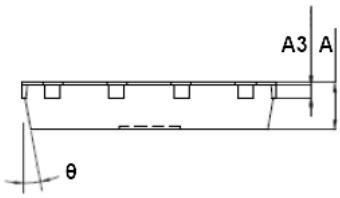

Figure 11. Unclamped Inductive Switching Waveform

**Mechanical Dimensions for PDFN5060-8L**

COMMON DIMENSIONS



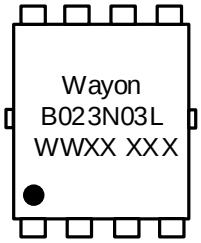




| SYMBOL | MM | |
|---|---|---|
| | MIN | MAX |
| A | 0.90 | 1.20 |
| A3 | 0.15 | 0.35 |
| D | 4.80 | 5.40 |
| E | 5.90 | 6.35 |
| D1 | 3.61 | 4.31 |
| E1 | 3.30 | 3.92 |
| E2 | 5.65 | 6.06 |
| k | 1.10 | - |
| b | 0.30 | 0.51 |
| e | 1.27BSC | |
| L | 0.38 | 0.71 |
| L1 | 0.05 | 0.36 |
| H | 0.38 | 0.61 |
| θ | 0° | 12° |

## Ordering Information

| Part | Package | Marking | Packing method |
|---|---|---|---|
| WMB023N03LG2 | PDFN5060-8L | B023N03L | Tape and Reel |

## Marking Information




B023N03L = Device code

WWXX XXX= Date code

## Contact Information

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